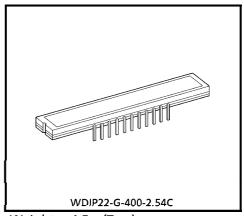
TOSHIBA **TCD2253D**

TOSHIBA CCD LINEAR IMAGE SENSOR CCD (Charge Coupled Device)

T C D 2 2 5 3 D

The TCD2253D is a high sensitive and low dark current 2700 elements x 3 line CCD color image sensor which includes CCD drive circuit, clamp circuit and sample & hold circuit.

The sensor is designed for scanner. The device contains a row of 2700 elements x 3 line photodiodes which provide a 12 lines/mm (300DPI) across a A4 size paper. The device is operated by 5V pulse and 12V power supply.



Weight: 4.5g (Typ.)

FEATURES

Number of Image Sensing Elements

: 2700 elements x 3 line

Image Sensing Element Size : $10.5 \mu \text{m}$ by $10.5 \mu \text{m}$ on $10.5 \mu \text{m}$

centers

Photo Sensing Region : High sensitive and low dark current

PN photodiode

Distance Between Photodiode Array: 42 µm (4 lines)

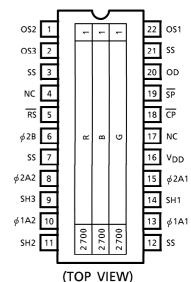
Clock : 2 phase (5V)

Internal Circuit : Sample & Hold circuit, Clamp circuit

Package : 22 pin CERDIP package

Color Filter : Red, Green, Blue

PIN CONNECTION



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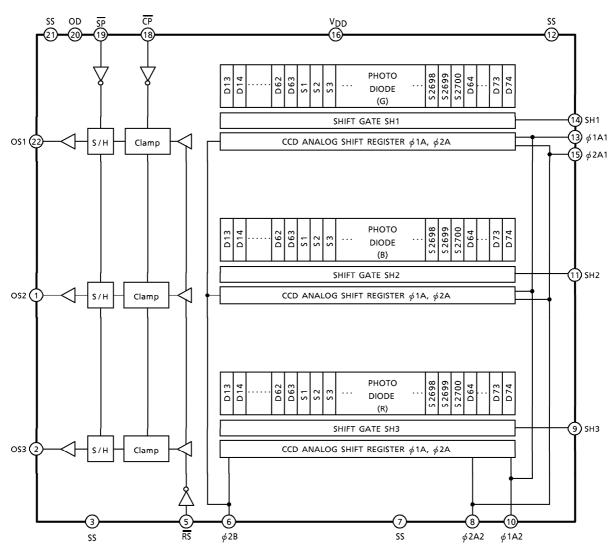
The information contained herein is subject to change without notice.

MAXIMUM RATINGS (Note 1)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Clock Pulse Voltage	Vφ		٧
Shift Pulse Voltage	VsH		
Reset Pulse Voltage	VRS	- 0.3~8.0	
Sample and Hold	V <u>SP</u>	-0.5~8.0	
Pulse Voltage	\ \ASP		
Clamp Pulse Voltage	VCP		
Power Supply Voltage	V _{OD}	-0.3~15	V
L Supply voltage	V _{DD}	- 0.5 - 15	"
Operating Temperature	T _{opr}	0~60	°C
Storage Temperature	T _{stg}	- 25∼85	°C

(Note 1) All voltage are with respect to SS terminals (Ground).

CIRCUIT DIAGRAM



TOSHIBA TCD2253D

PIN NAMES

PIN No.	SYMBOL	NAME	PIN No.	SYMBOL	NAME
1	OS2	Signal Output 2 (Blue)	12	OS1	Signal Output 1 (Green)
2	OS3	Signal Output 3 (Red)	13	SS	Ground
3	SS	Ground	14	OD	Power (Analog)
6	NC	Non Connection	15	SP	Sample and Hold Gate
5	RS	Reset Gate	16	CP	Clamp Gate
6	φ2B	Final Stage Clock (Phase 2)	17	NC	Non Connection
7	SS	Ground	18	V_{DD}	Power (Digital)
8	φ2A2	Clock 2 (Phase 2)	19	φ2A1	Clock 1 (Phase 2)
9	SH3	Shift Gate 3	20	SH1	Shift Gate 1
10	φ1A2	Clock 2 (Phase 1)	21	φ1A1	Clock 1 (Phase 1)
11	SH2	Shift Gate 2	22	SS	Ground

OPTICAL / ELECTRICAL CHARACTERISTICS

(Ta = 25°C, V_{OD} = 12V, V ϕ = V_{RS} = V_{SH} = V_{CP} = 5V (pulse), f ϕ = 1.0MHz, f $\overline{\text{RS}}$ = 1.0MHz, LOAD RESISTANCE = 100k Ω , t_{INT} (INTEGRATION TIME) = 10ms, LIGHT SOURCE = A LIGHT SOURCE + CM500S FILTER (t = 1.0mm))

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	NOTE
	R _R	12.2	17.4	22.6		
Sensitivity	RG	17.4	24.8	32.2	V / (lx·s)	(Note 2)
	R _B	5.2	7.4	9.6		
Photo Response Non Uniformity	PRNU (1)	_	10	20	%	(Note 3)
Photo Response Non-Onnormity	PRNU (3)	_	3	12	mV	(Note 4)
Saturation Output Voltage	V _{SAT}	3.0	3.5	_	٧	(Note 5)
Saturation Exposure	SE	0.17	0.14	_	lx∙s	(Note 6)
Dark Signal Voltage	V _{DRK}	_	2.0	6.0	mV	(Note 7)
Dark Signal Non Uniformity	DSNU	_	4.0	14.0	mV	(Note 7)
DC Power Dissipation	PD	_	200	400	mW	
Total Transfer Efficiency	TTE	92	_	_	%	
Output Impedance	Z _o	_	0.5	1.0	kΩ	
DC Signal Output Voltage	Vos	3.5	5.0	7.0	V	(Note 8)
Random Noise	Ν _D σ	_	1.2	_	mV	(Note 9)
Reset Noise	V _{RS}	_	2.1	_	V	(Note 8)

- (Note 2) Sensitivity is defined for each color of signal outputs average when the photosensitive surface is applied with the light of uniform illumination and uniform color temperature.
- (Note 3) PRNU (1) is defined for each color on a single chip by the expressions below when the photosensitive surface is applied with the light of uniform illumination and uniform color temperature.

PRNU (1) =
$$\frac{\Delta \chi}{\overline{\chi}}$$
 × 100 (%)

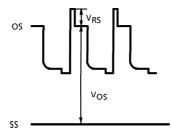
When $\overline{\chi}$ is average of total signal outputs and $\Delta \chi$ is the maximum deviation from $\overline{\chi}$. The amount of incident light is shown below.

Red =
$$\frac{1}{2}$$
 SE, Green = $\frac{1}{2}$ SE, Blue = $\frac{1}{4}$ SE

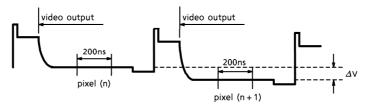
- (Note 4) PRNU (3) is defined as maximum voltage with next pixel, where measured 5% of SE (Typ.).
- (Note 5) $V_{\mbox{SAT}}$ is defined as minimum saturation output of all effective pixels.
- (Note 6) Definition of SE : $SE = \frac{V_{SAT}}{R_{G}}$ (Ix·s)
- (Note 7) V_{DRK} is defined as average dark signal voltage of all effective pixels. DSNU is defined as different voltage between V_{DRK} and V_{MDK} when V_{MDK} is maximum dark signal voltage.



(Note 8) DC signal Output Voltage Reset Noise is defined as follows, but Reset Noise is a fixed pattern noise.



(Note 9) Random noise is defined as the standard deviation (sigma) of the output level difference between two adjacent effective pixels under no illumination (i.e. dark conditions) calculated by the following procedure.



Output wave form (Effective pixels under dark condition)

- 1) Two adjacent pixels (pixel n and n + 1) in one reading are fixed as measurement points.
- 2) Each of the output level at video output periods averaged over 200ns period to get V(n) and V(n+1).
- 3) V(n + 1) is subtracted from V(n) to get ΔV .

$$\Delta V = V(n) - V(n + 1)$$

4) The standard deviation of ΔV is calculated after procedure 2) and 3) are repeated 30 times (30 readings).

$$\Delta V = \frac{1}{30} \sum_{i=1}^{30} |\Delta Vi| \qquad \sigma = \sqrt{\frac{1}{30} \sum_{i=1}^{30} (|\Delta Vi| - \overline{\Delta V})^2}$$

- 5) Procedure 2), 3) and 4) are repeated 10 times to get 10 sigma values.
- 6) 10 sigma values are averaged.

$$\overline{\sigma} = \frac{1}{10} \sum_{j=1}^{10} \sigma_j$$

7) $\overline{\sigma}$ value calculated using the above procedure is observed $\sqrt{2}$ times larger than that measured relative to the ground level. So we specify the random noise as follows.

$$N_{D\sigma} = \frac{1}{\sqrt{2}} \overline{\sigma}$$

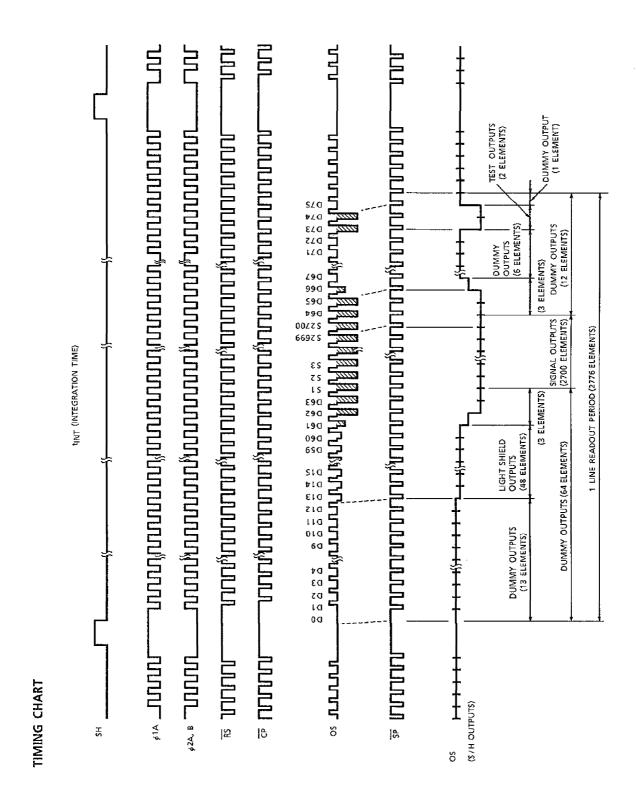
OPERATING CONDITION

CHARACTERISTI	С	SYMBOL	MIN.	TYP.	MAX.	UNIT	NOTE
Clock Pulse Voltage	"H"Level	V	4.5	5.0	5.5	V	
Clock Pulse Voltage	"L" Level	Vφ2A	0	_	0.5	\ \ \	
Final Stage Clock Pulse	"H"Level	V//2B	4.5	5.0	5.5	V	
Voltage	"L" Level	V∮2B	0	0	0.5	V	
Shift Pulse Voltage	"H"Level	Vari	V <i>∮</i> A″H″-0.5	V <i></i> ∕ A"H"	V <i></i> ∕ A"H"	V	(Note 10)
Shirt Pulse Voltage	"L" Level	V _{SH}	0	0	0.5	V	(Note 10)
Booot Bulso Valtage	"H"Level	\/55	4.5	5.0	5.5	<	
Reset Pulse Voltage	"L" Level	VRS	0	0	0.5		
Sample and Hold Pulse	"H"Level	\/==	4.5	5.0	5.5	V	(Note 11)
Voltage	"L" Level	VSP	0	0	0.5	\ \ \	(Note 11)
Claren Bulsa Valtara	"H"Level	V==	4.5	5.0	5.5	V	
Clamp Pulse Voltage	"L" Level	VCP	0	0	0.5	\ \	
Power Supply Voltage (An	alog)	V _{OD}	11.4	12.0	13.0	V	
Power Supply Voltage (Di	gtal)	V_{DD}	11.4	12.0	13.0	V	

(Note 10) $V\phi A"H"$ means the high level voltage of $V\phi A$ when SH pulse is high level. (Note 11) Supply "L" Level to \overline{SP} terminal when sample and hold circuitry is not used.

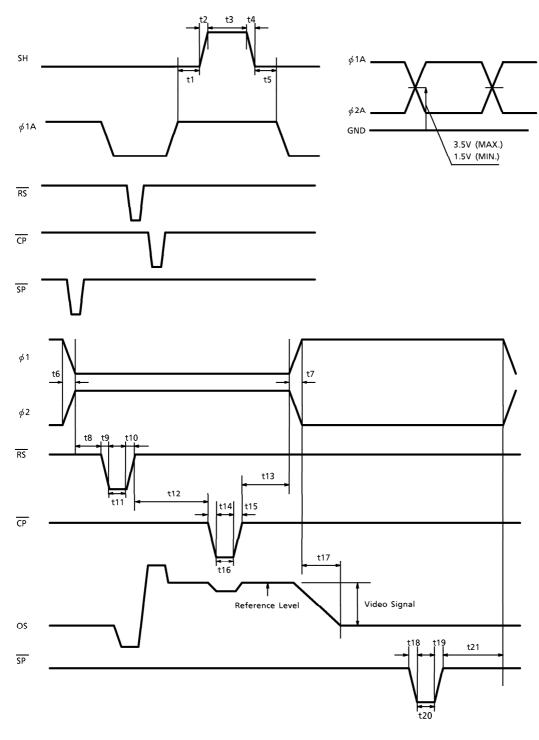
CLOCK CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT
Clock Pulse Frequency	fφ	_	1.0	5.0	MHz
Reset Pulse Frequency	fRS	_	1.0	5.0	MHz
Clamp Pulse Frequency	f C P	_	1.0	5.0	MHz
Sample and Hold Pulse Frequency	f <u>√</u> F	_	1.0	5.0	MHz
Clock Capacitance	СфА	_	250	400	pF
Final Stage Clock Capacitance	С∮В	_	10	20	pF
Shift Gate Capacitance	CSH	_	50	100	pF
Reset Gate Capacitance	CRS	_	10	20	pF
Clamp Gate Capacitance	CCP	_	10	20	pF
Sample and Hold Gate Capacitance	CSP	_	10	20	pF



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TIMING REQUIREMENTS (LINE CLAMP MODE)



TIMING REQUIREMENTS (Cont.)

CHARACTERISTIC	SYMBOL	MIN.	TYP. (Note 14)	MAX.	UNIT
Dulco Timing of SII and 11	t1	120	1000	_	ns
Pulse Timing of SH and ϕ 1	t5	200	1000	_	
SH Pulse Rise Time, Fall Time	t2, t4	0	50	_	ns
SH Pulse Width	t3	1000	2000	_	ns
ϕ 1, ϕ 2 Pulse Rise Time, Fall Time	t6, t7	0	50	_	ns
Pulse Timing of ϕ 2B and \overline{RS}	t8	20	40	_	ns
RS Pulse Rise Time, Fall Time	t9, t10	0	20	_	ns
RS Pulse Width	t11	40	80	_	ns
Pulse Timing of RS and CP	t12	60	80	_	ns
Pulse Timing of ϕ 2B and $\overline{\sf CP}$	t13	0	20	_	ns
CP Pulse Rise Time, Fall Time	t14, t15	0	20	_	ns
CP Pulse Width	t16	30	80	_	ns
Video Data Delay Time (Note 13)	t17	_	60	_	ns
SP Pulse Rise Time, Fall Time	t18, t19	0	20	_	ns
SP Pulse Width	t20	45	80	_	ns
Pulse Timing of RS and SP	t21	0	20	_	ns

(Note 12) TYP. is the case of $f_{\overline{RS}} = 1.0 MHz$.

(Note 13) Load Resistance is $100k\Omega$.

APPLICATION NOTE

Mode Select

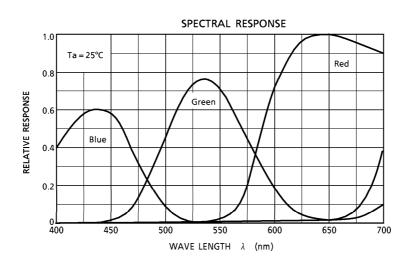
1. Sample & Hold

ON	OFF
SP Pulse	SP = Low

2. Clamp Mode

Bit Clamp	Line Clamp
CP Pulse	$\overline{CP} = \overline{SH}$

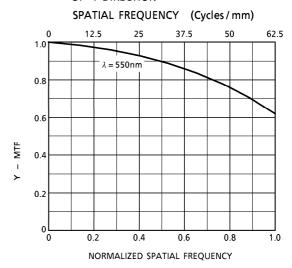
TYPICAL SPECTRAL RESPONSE



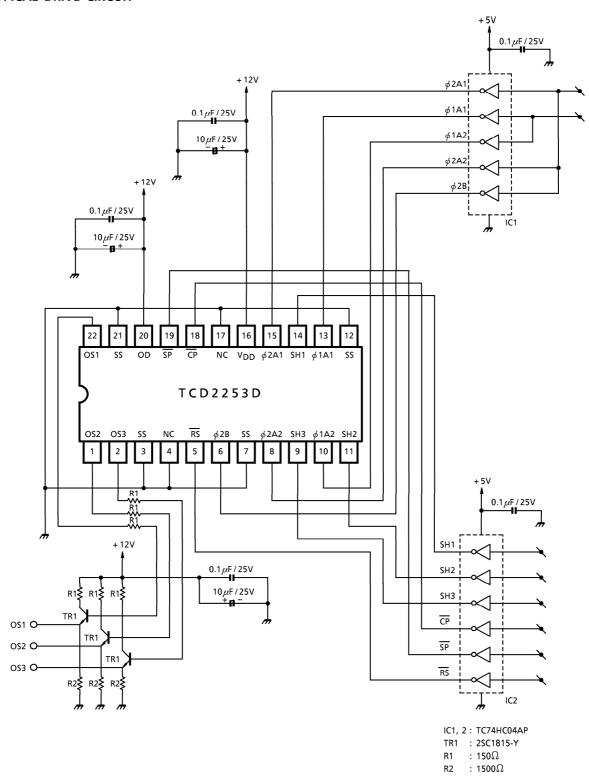
MODULATION TRANSFER FUNCTION OF X-DIRECTION

SPATIAL FREQUENCY (Cycles/mm) 12.5 25 37.5 50 62.5 1.0 $\lambda = 550 \text{nm}$ 0.8 0.6 X - MTF 0.4 0.2 0.2 0.4 0.6 1.0 NORMALIZED SPATIAL FREQUENCY

MODULATION TRANSFER FUNCTION OF Y-DIRECTION



TYPICAL DRIVE CIRCUIT



1998-09-24 11/13

CAUTION

1. Window Glass

The dust and stain on the glass window of the package degrade optical performance of CCD sensor

Keep the glass window clean by saturating a cotton swab in alcohol and lightly wiping the surface, and allow the glass to dry, by blowing with filtered dry N2.

Care should be taken to avoid mechanical or thermal shock because the glass window is easily to damage.

2. Electrostatic Breakdown

Store in shorting clip or in conductive foam to avoid electrostatic breakdown.

3. Incident Light

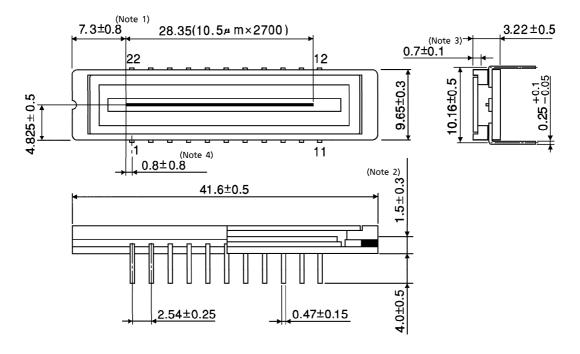
CCD sensor is sensitive to infrared light.

Note that infrared light component degrades resolution and PRNU of CCD sensor.

4. Lead Frame Forming

Since this package is not strong against mechanical stress, you should not reform the lead frame. We recommend to use a IC-inserter when you assemble to PCB.

OUTLINE DRAWING



(Note 1) No.1 SENSOR ELEMENT (S1) TO EDGE OF PACKAGE.

(Note 2) TOP OF CHIP TO BOTTOM OF PACKAGE.

(Note 3) GLASS THICKNESS (n = 1.5)

(Note 4) No.1 SENSOR ELEMENT (S1) TO EDGE OF No.1 PIN.

Weight: 4.5g (Typ.)